

To: All Concerned Customer

Subject: Post Board Mount Cleaning of Pericom Semiconductor IC and FCP products

Pericom's products have never been known to exhibit any adverse effect to the operating capability of our devices when subjected to the following cleaning methods and conditions: Ultrasonic (not recommended for FCP) Dip Spray Steam Telpene

Regarding our IC QFNs, no clean solder paste is recommended due to low standoff height.

If any other information on this issue is required, please contact Pericom Customer Question group (<u>pca_customerquestion@diodes.com</u>) at your convenience.

Sincerely,

Raul Aman Director, Quality Assurance E-mail: <u>Raul_Aman@diodes.com</u>